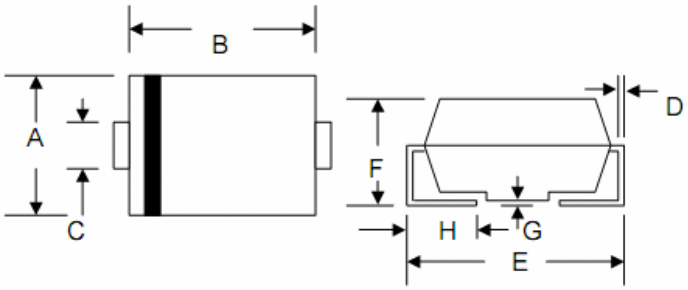
**Technical Data**
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## Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 100A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request




| SMC/DO-214AB | | | | |
|---|---|---|---|---|
| Dim | Min | Max | Min | Max |
| A | 5.59 | 6.22 | 0.220 | 0.245 |
| B | 6.60 | 7.11 | 0.260 | 0.280 |
| C | 2.75 | 3.25 | 0.108 | 0.128 |
| D | 0.15 | 0.31 | 0.006 | 0.012 |
| E | 7.75 | 8.13 | 0.305 | 0.320 |
| F | 2.00 | 2.62 | 0.079 | 0.103 |
| G | 0.05 | 0.20 | 0.002 | 0.008 |
| H | 0.76 | 1.27 | 0.030 | 0.050 |
| | In mm | | In inch | |

## Mechanical Data

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.21 grams (approx.)

## Marking Diagram:




Where XXXXX is YYWWL

SK32 = Part Name
YY = Year
WW = Week
L = Lot Number

**Cautions**: Molding resin
Epoxy resin UL:94V-0

## Ordering Information:

| Device | Package | Shipping |
|---|---|---|
| SK32-G-SK310-G | SMC (Pb-Free) | 3000pcs / reel |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

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## Maximum Ratings and Electrical Characteristics @$T_A$=25°C unless otherwise specified

| Characteristic | Symbol | SK32-G | SK33-G | SK34-G | SK35-G | SK36-G | SK38-G | SK39-G | SK310-G | Unit |
|---|---|---|---|---|---|---|---|---|---|---|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 20 | 30 | 40 | 50 | 60 | 80 | 90 | 100 | V |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 14 | 21 | 28 | 35 | 42 | 56 | 64 | 71 | V |
| Average Rectified Output Current @$T_L$ = 75°C | $I_O$ | 3.0 | | | | | | | | A |
| Non-Repetitive Peak Forward Surge Current<br>8.3ms Single half sine-wave superimposed on rated load (JEDEC Method) | $I_{FSM}$ | 100 | | | | | | | | A |
| Forward Voltage @$I_F$ = 3.0A | $V_{FM}$ | 0.55 | | | 0.75 | | 0.85 | | | V |
| Peak Reverse Current @$T_A$ = 25°C<br>At Rated DC Blocking Voltage @$T_A$ = 100°C | $I_{RM}$ | 0.5<br>20 | | | | | | | | mA |
| Typical Thermal Resistance Junction to Ambient (Note 1) | $R_{\theta JA}$ | 55 | | | | | | | | K/W |
| Operating Temperature Range | $T_j$ | -65 to +125 | | | | | | | | °C |
| Storage Temperature Range | $T_{STG}$ | -65 to +150 | | | | | | | | °C |

Note: 1. Mounted on P.C. Board with 14mm$^2$ copper pad areas

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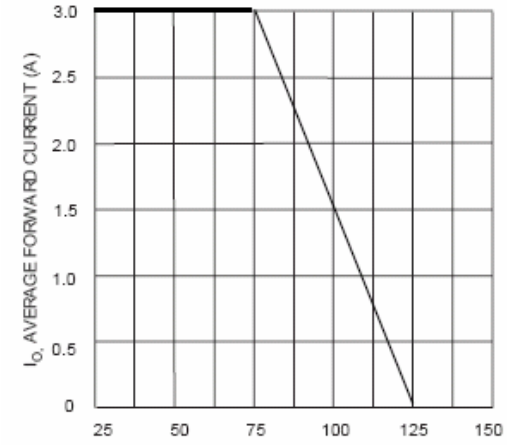



Fig. 1 Forward Current Derating Curve

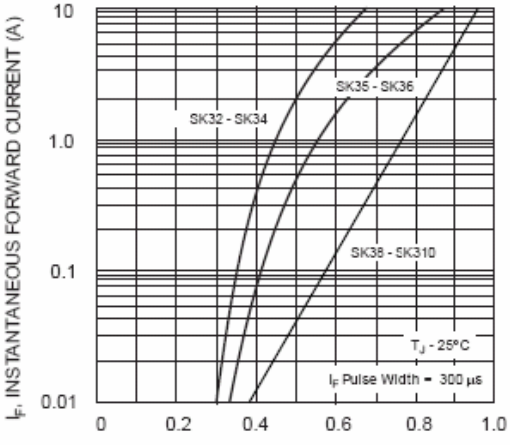
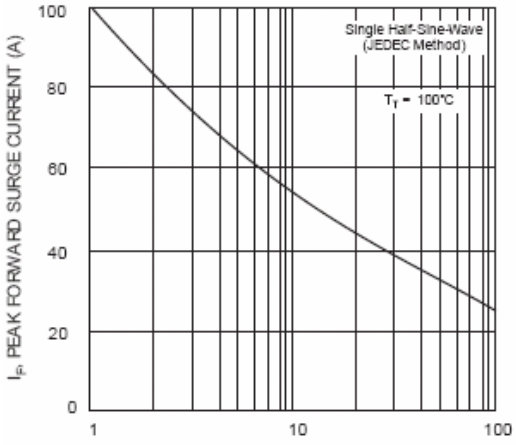



Fig. 2 Typical Forward Characteristics




Fi . 3 Max Non-Repetitive Peak Fwd Sur e Current

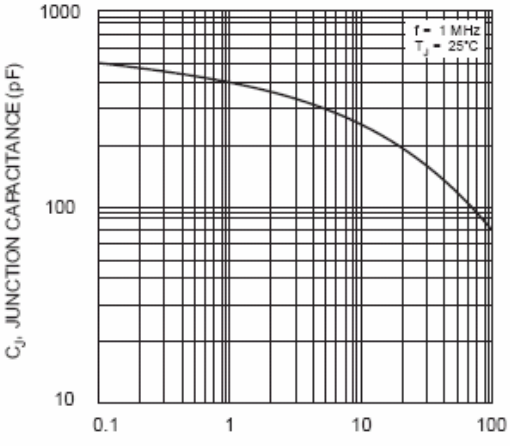



Fig. 4 Typical Junction Capacitance

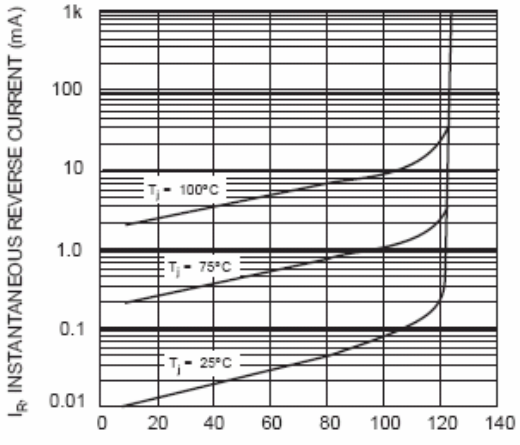



Fig. 5 Typical Reverse Characteristics

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